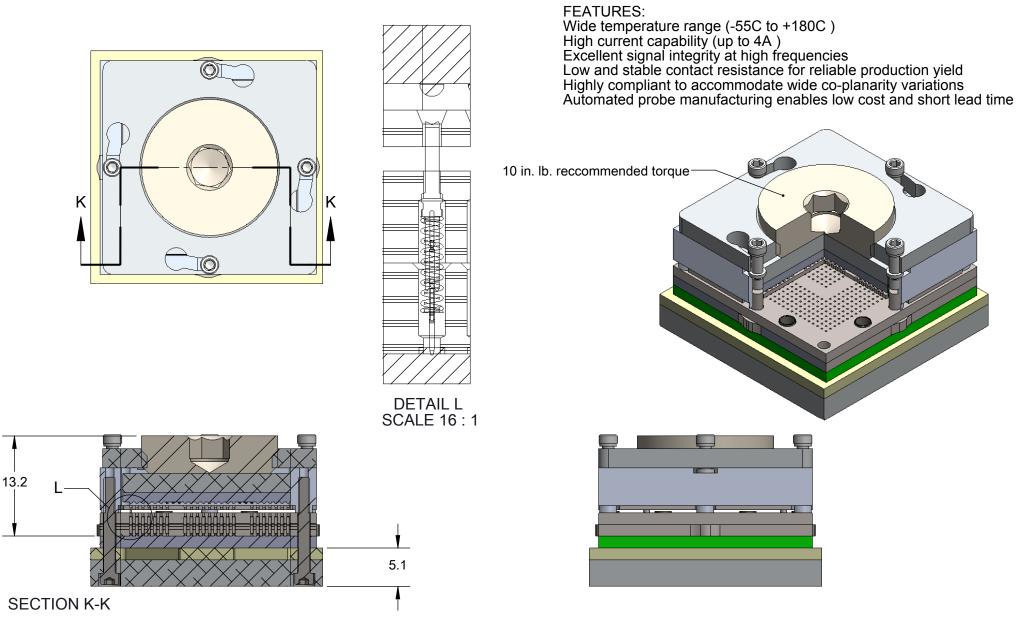
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

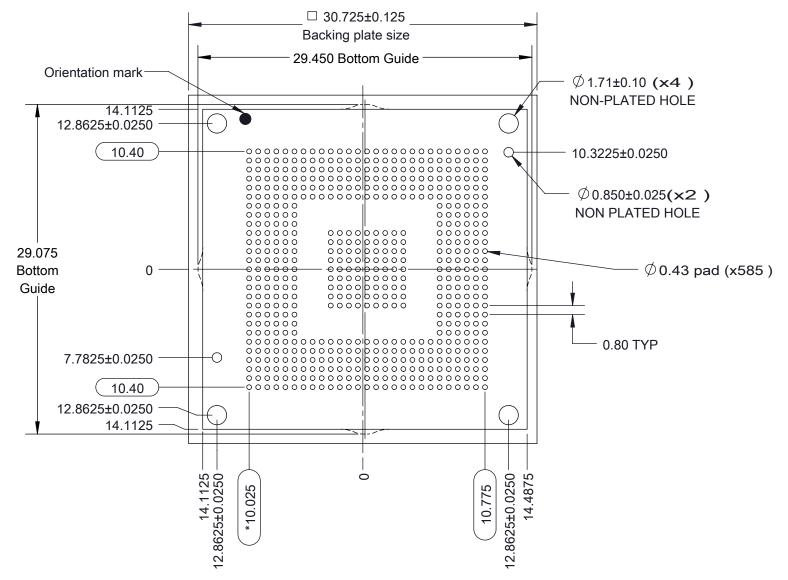


Description: SBT-BGA585 for 23x23mm 0.8mm pitch 27x27 array

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-6515 Drawing		Material: N/A	STATUS: Released	SHEET: 1 OF 5	REV. B SCALE: 2:1
•	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 31.51	ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 2:1
			FILE: SBT-BGA-6515	DATE: 6/6/13	

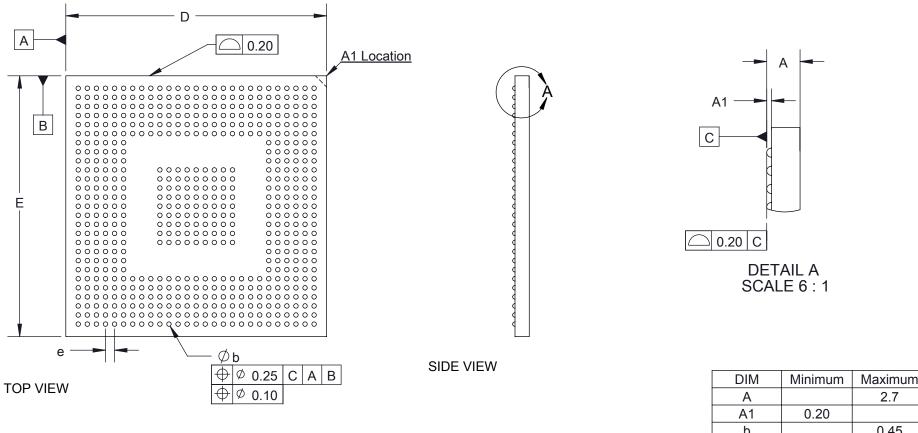


Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances</u>: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Target PCB Recommendations Total thickness: 1.6mm min. Plating: Gold or Solder finish PCB Pad height: Same or higher than solder mask

SI	BT-BGA-6515 Drawing		STATUS: Released	SHEET: 2 OF 5	REV. B
		Finish: N/A Weight: 31.51	ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 3:1
			FILE: SBT-BGA-6515	DATE: 6/6/13	



Ironwood Package code: BGA585B

DIM	Minimum	Maximum	
A		2.7	
A1	0.20		
b		0.45	
D	D 23.00 BSC		
E	23.00	23.00 BSC	
e 0.80 BSC			
ARRAY	27 X 27		
PIN COUN	Г	585	

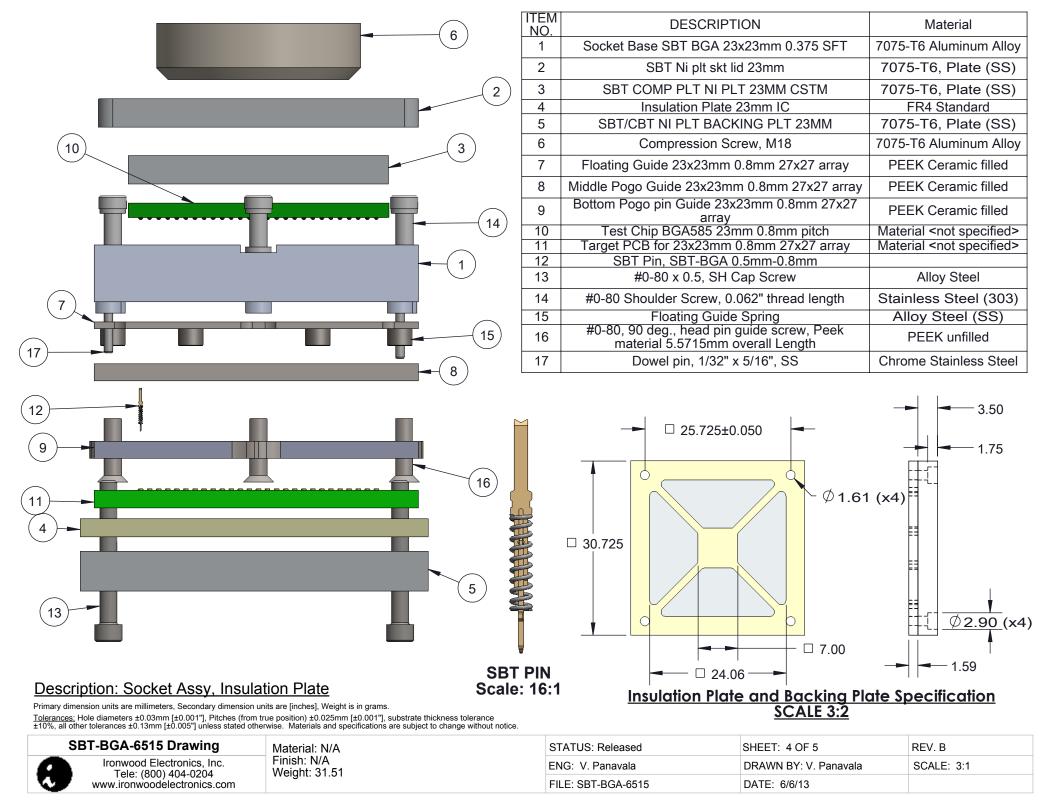
- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
- 4. Datum C (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Compatible BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ± 0.03 mm [± 0.001 "], Pitches (from true position) ± 0.025 mm [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-6515 Drawing	Finish: N/A Weight: 31.51	STATUS: Released	SHEET: 3 OF 5	REV. B
Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 3:1
www.ironwoodelectronics.com		FILE: SBT-BGA-6515	DATE: 6/6/13	



Re v			Description
В	2/25/15	RP/MR	Changed spring pin and guides to new design, dowel pin protrusion adjusted, if needed, metal screws replaced with plastic screws, if needed. Contact Ironwood for details.

Description: Revisions

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances</u>: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-6515 Drawing		Material:	STATUS: Released	SHEET: 5 OF 5	REV. B
•	©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: Weight:	ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 3:1
		Woight.	FILE: SBT-BGA-6515	DATE: 6/6/13	